

Project Titan: Q3 Performance Report

This document contains sensitive data regarding the semiconductor yield rates.

Column A (Process):

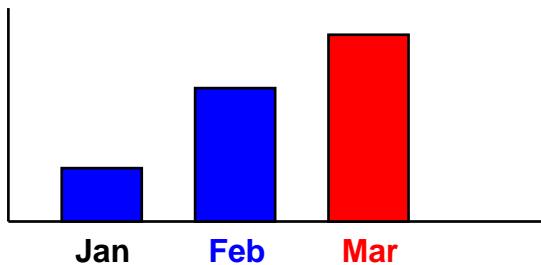
1. Etching started.
2. Doping completed.
3. Wafer polished.

Column B (Status):

- FAILED - Stop immediately.
SUCCESS - Proceed.
PENDING - Wait for QA.

Device Type	Batch ID	Yield (%)	Defect Density
SiC MOSFET	B-101	45%	High
GaN HEMT	B-102	82%	Low
IGBT	B-103	91%	Very Low

Figure 1: Monthly Energy Consumption (Visual Only)



WARNING: CODE RED